

Designer's Data Sheet
Power Field Effect Transistor
N-Channel Enhancement-Mode
Silicon Gate TMOS

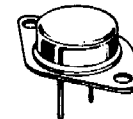
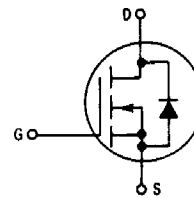


MTM45N15

TMOS POWER FET
45 AMPERES
 $r_{DS(on)} = 0.06 \text{ OHM}$
150 VOLTS

This TMOS Power FET is designed for medium voltage, high speed power switching applications such as switching regulators, converters, solenoid and relay drivers.

- Silicon Gate for Fast Switching Speeds — Switching Times Specified at 100°C
- Designer's Data — I_{DSS} , $V_{DS(on)}$, $V_{GS(th)}$ and SOA Specified at Elevated Temperature
- Rugged — SOA is Power Dissipation Limited
- Source-to-Drain Diode Characterized for Use With Inductive Loads



TO-204AE

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	150	Vdc
Drain-Gate Voltage ($R_{GS} = 1 \text{ M}\Omega$)	V_{DGR}	150	Vdc
Gate-Source Voltage	V_{GS}	± 20	Vdc
Continuous	V_{GSM}	± 40	Vpk
Non-repetitive ($t_p \leq 50 \mu s$)			
Drain Current — Continuous	I_D	45	Adc
— Pulsed	I_{DM}	225	
Total Power Dissipation (@ $T_C = 25^\circ C$)	P_D	250	Watts
Derate above 25°C		2	W/°C
Operating and Storage Temperature Range	T_J, T_{stg}	-65 to 150	°C

THERMAL CHARACTERISTICS

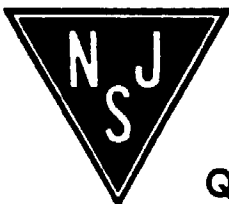
Thermal Resistance — Junction to Case	$R_{\theta JC}$	0.5	°C/W
— Junction to Ambient	$R_{\theta JA}$	30	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 5 seconds	T_L	275	°C

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ C$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Drain-Source Breakdown Voltage ($V_{GS} = 0, I_D = 0.25 \text{ mA}$)	$V_{(BR)DSS}$	150	—	Vdc
Zero Gate Voltage Drain Current ($V_{DS} = \text{Rated } V_{DSS}, V_{GS} = 0$)	I_{DSS}	—	10	μAdc
($V_{DS} = \text{Rated } V_{DSS}, V_{GS} = 0, T_J = 125^\circ C$)		—	100	
Gate-Body Leakage Current, Forward ($V_{GSF} = 20 \text{ Vdc}, V_{DS} = 0$)	I_{GSSF}	—	100	nAdc
Gate-Body Leakage Current, Reverse ($V_{GSR} = 20 \text{ Vdc}, V_{DS} = 0$)	I_{GSSR}	—	100	nAdc

(continued)

Designer's Data for "Worst Case" Conditions — The Designer's Data Sheet permits the design of most circuits entirely from the information presented. Limit curves — representing boundaries on device characteristics — are given to facilitate "worst case" design.



Quality Semi-Conductors